

Title (en)
Compact design relay.

Title (de)
Kompaktes Relais.

Title (fr)
Relais compact.

Publication
EP 0053870 A1 19820616 (EN)

Application
EP 81303143 A 19810709

Priority
JP 17542180 U 19801205

Abstract (en)
In a compact design relay, in which gaps between a base member (2) and a case member (3) covering the base member and between the base member (2) and terminal pins (1) mounted on the base member are sealed by filling the gaps with an adhesive (4) which is thermally hardened thereafter, a small air vent hole (5) is formed in part of the case member (3) and/or base member (2) free from the adhesive (4) and is sealed with a further adhesive (8) after the thermal hardening treatment of the first-mentioned adhesive (4).

IPC 1-7
H01H 50/02

IPC 8 full level
H01H 45/02 (2006.01); **G06Q 10/08** (2024.01); **H01H 50/02** (2006.01)

CPC (source: EP)
H01H 50/023 (2013.01)

Citation (search report)

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- GB 2029107 A 19800312 - BOSCH GMBH ROBERT
- DE 2908887 A1 19790913 - IDEC IZUMI CORP
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EP0118841A3; EP0713233A3; EP0351547A3; GB2120853A; EP0130500A3; US4580005A; EP0110098A1; AU568369B2

Designated contracting state (EPC)
DE FR GB IT

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